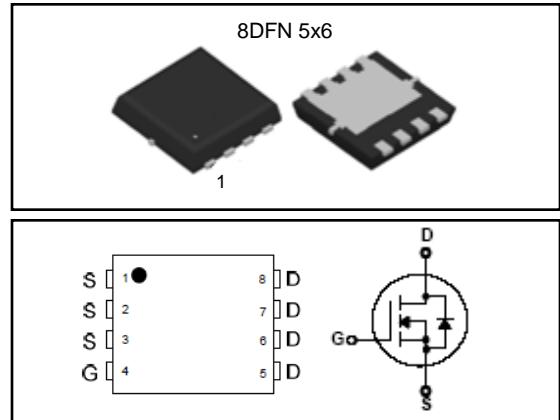


## HRLF125N06K 60V N-Channel Trench MOSFET

### FEATURES

- $BV_{DSS} = 60\text{ V}$
- $I_D = 70\text{ A}$
- Unrivalled Gate Charge : 50 nC (Typ.)
- Lower  $R_{DS(ON)}$  : 10 mΩ (Typ.) @  $V_{GS}=10\text{V}$
- Lower  $R_{DS(ON)}$  : 12 mΩ (Typ.) @  $V_{GS}=4.5\text{V}$
- 100% Avalanche Tested



### Absolute Maximum Ratings $T_C=25^\circ\text{C}$ unless otherwise specified

Symbol	Parameter	Value	Units
$V_{DSS}$	Drain-Source Voltage	60	V
$I_D$	Drain Current – Continuous ( $T_C = 25^\circ\text{C}$ )	70 *	A
	Drain Current – Continuous ( $T_C = 100^\circ\text{C}$ )	49 *	A
$I_{DM}$	Drain Current – Pulsed (Note 1)	245 *	A
$V_{GS}$	Gate-Source Voltage	$\pm 25$	V
$E_{AS}$	Single Pulsed Avalanche Energy (Note 2)	145	mJ
$E_{AR}$	Repetitive Avalanche Energy (Note 1)	7.5	mJ
$P_D$	Power Dissipation ( $T_C = 25^\circ\text{C}$ )	75	W
	Power Dissipation ( $T_A = 25^\circ\text{C}$ )	2.4	W
$T_J, T_{STG}$	Operating and Storage Temperature Range	-55 to +175	$^\circ\text{C}$
$T_L$	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	300	$^\circ\text{C}$

\* Drain current limited by maximum junction temperature

### Thermal Resistance Characteristics

Symbol	Parameter	Typ.	Max.	Units
$R_{\theta JA}$	Junction-to-Ambient	--	62	$^\circ\text{C}/\text{W}$
$R_{\theta JC}$	Junction-to-Case	--	2.0	

**Electrical Characteristics**  $T_J=25^\circ\text{C}$  unless otherwise specified

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
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**On Characteristics**

$V_{GS}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	1.0	--	2.4	V
$R_{DS(\text{ON})}$	Static Drain-Source On-Resistance	$V_{GS} = 10 \text{ V}, I_D = 15 \text{ A}$	--	10	12.5	$\text{m}\Omega$
		$V_{GS} = 4.5 \text{ V}, I_D = 10 \text{ A}$	--	12	15	$\text{m}\Omega$
$g_{FS}$	Forward Transconductance	$V_{DS} = 15, I_D = 15 \text{ A}$	--	60	--	S

**Off Characteristics**

$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	60	--	--	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 48 \text{ V}, V_{GS} = 0 \text{ V}$	--	--	1	$\mu\text{A}$
		$V_{DS} = 48 \text{ V}, T_J = 125^\circ\text{C}$	--	--	100	$\mu\text{A}$
$I_{GSS}$	Gate-Body Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$	--	--	$\pm 100$	nA

**Dynamic Characteristics**

$C_{iss}$	Input Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V}, f = 1.0 \text{ MHz}$	--	2700	--	pF
$C_{oss}$	Output Capacitance		--	230	--	pF
$C_{rss}$	Reverse Transfer Capacitance		--	180	--	pF
$R_g$	Gate Resistance	$V_{GS} = 0 \text{ V}, V_{DS} = 0 \text{ V}, f = 1\text{MHz}$	--	1.2	--	$\Omega$

**Switching Characteristics**

$t_{d(on)}$	Turn-On Time	$V_{DS} = 30 \text{ V}, I_D = 15 \text{ A}, R_G = 6 \Omega$	--	20	--	ns
$t_r$	Turn-On Rise Time		--	50	--	ns
$t_{d(off)}$	Turn-Off Delay Time		--	120	--	ns
$t_f$	Turn-Off Fall Time		--	40	--	ns
$Q_g$	Total Gate Charge	$V_{DS} = 48 \text{ V}, I_D = 15 \text{ A}, V_{GS} = 10 \text{ V}$	--	50	--	nC
$Q_{gs}$	Gate-Source Charge		--	7	--	nC
$Q_{gd}$	Gate-Drain Charge		--	13	--	nC

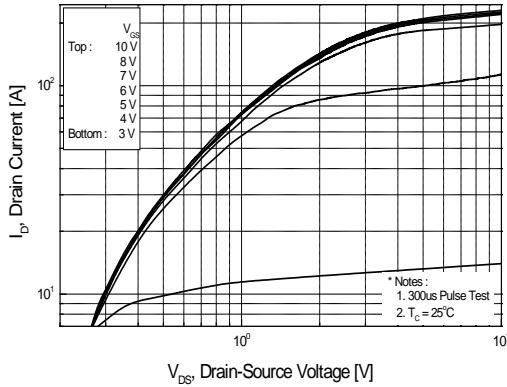
**Source-Drain Diode Maximum Ratings and Characteristics**

$I_S$	Continuous Source-Drain Diode Forward Current	--	--	70	A	
$I_{SM}$	Pulsed Source-Drain Diode Forward Current	--	--	245		
$V_{SD}$	Source-Drain Diode Forward Voltage	$I_S = 15 \text{ A}, V_{GS} = 0 \text{ V}$	--	--	1.3	V
$trr$	Reverse Recovery Time	$I_S = 15 \text{ A}, V_{GS} = 0 \text{ V}$ $dI_F/dt = 100 \text{ A}/\mu\text{s}$	--	40	--	ns
$Qrr$	Reverse Recovery Charge		--	40	--	nC

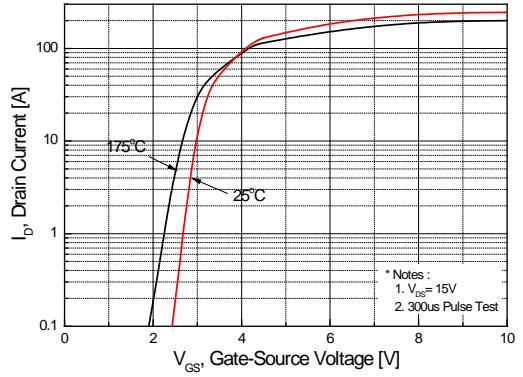
**Notes :**

- Repetitive Rating : Pulse width limited by maximum junction temperature
- $L=1\text{mH}$ ,  $I_{AS}=13\text{A}$ ,  $V_{DD}=25\text{V}$ ,  $R_G=25\Omega$ , Starting  $T_J=25^\circ\text{C}$

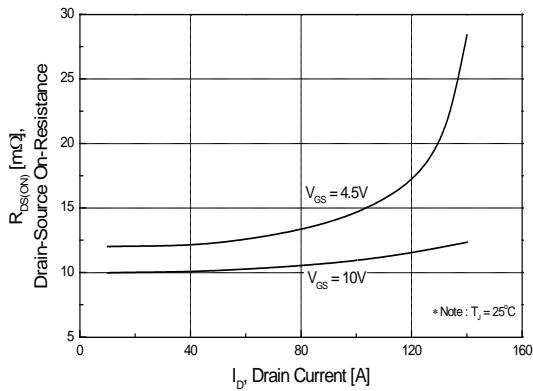
## Typical Characteristics



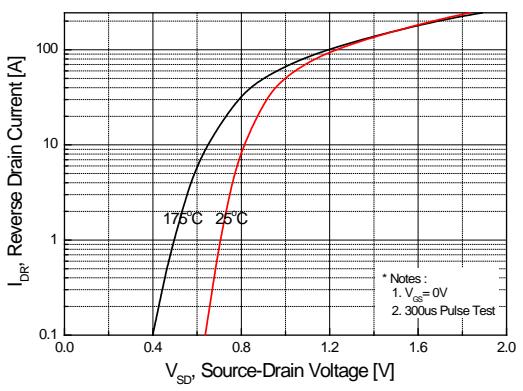
**Figure 1. On Region Characteristics**



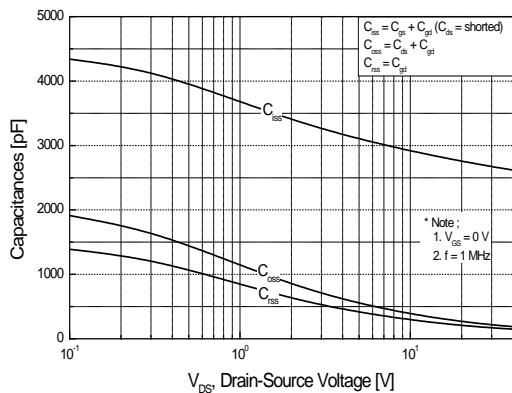
**Figure 2. Transfer Characteristics**



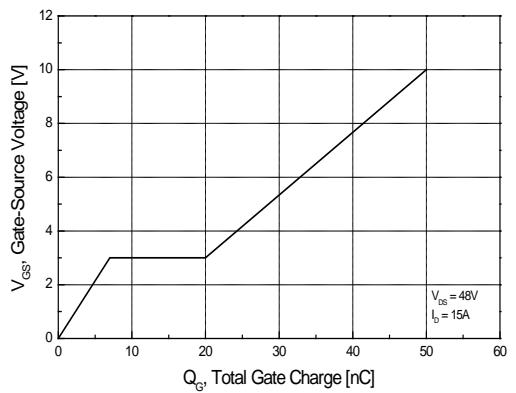
**Figure 3. On Resistance Variation vs. Drain Current and Gate Voltage**



**Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature**

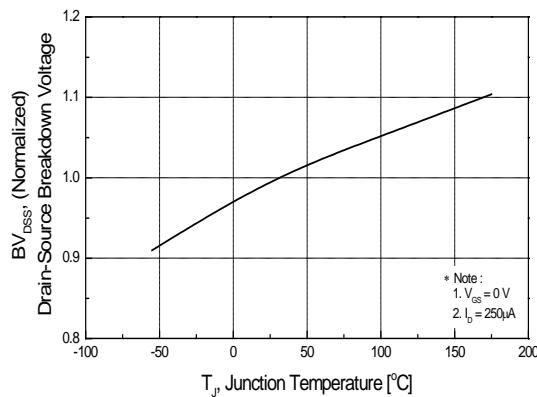


**Figure 5. Capacitance Characteristics**

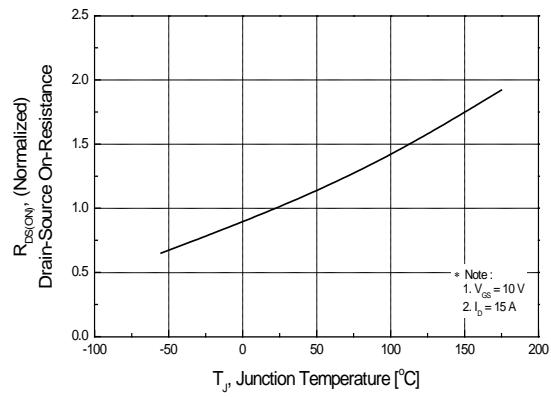


**Figure 6. Gate Charge Characteristics**

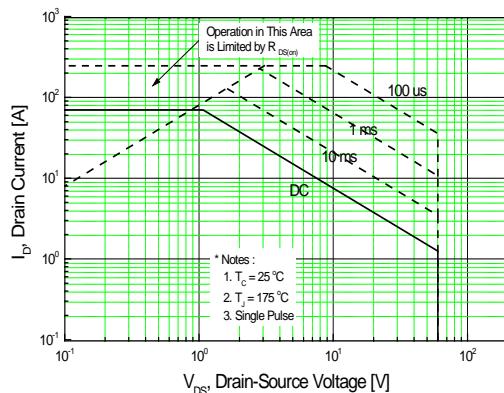
## Typical Characteristics (continued)



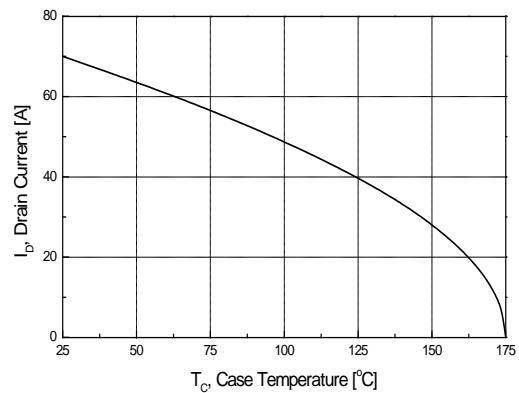
**Figure 7. Breakdown Voltage Variation vs Temperature**



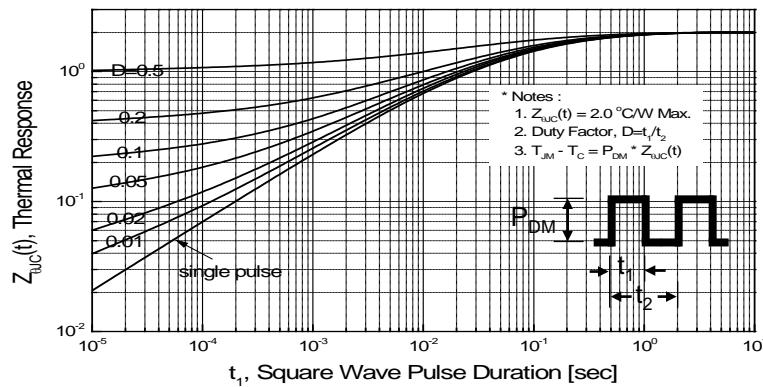
**Figure 8. On-Resistance Variation vs Temperature**



**Figure 9. Maximum Safe Operating Area**



**Figure 10. Maximum Drain Current vs Case Temperature**



**Figure 11. Transient Thermal Response Curve**

Fig 12. Gate Charge Test Circuit & Waveform

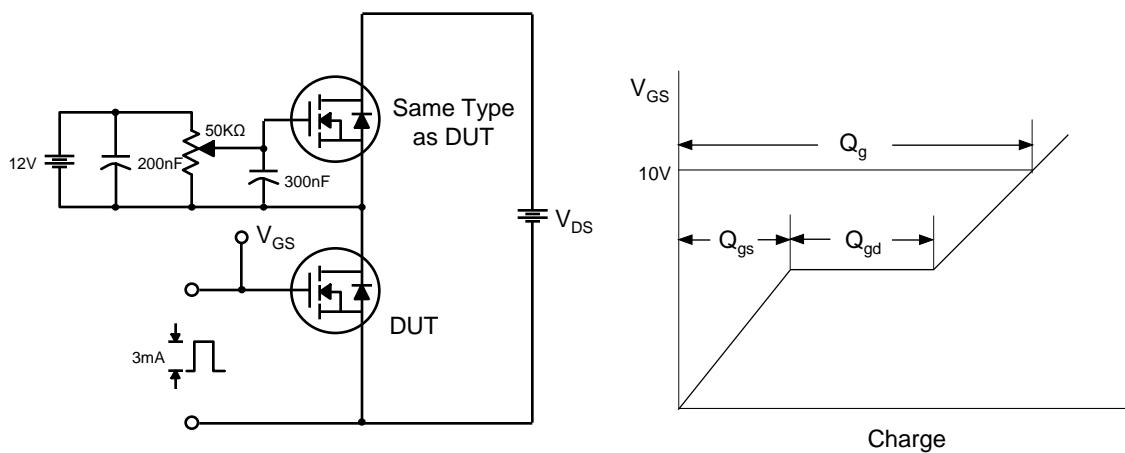


Fig 13. Resistive Switching Test Circuit & Waveforms

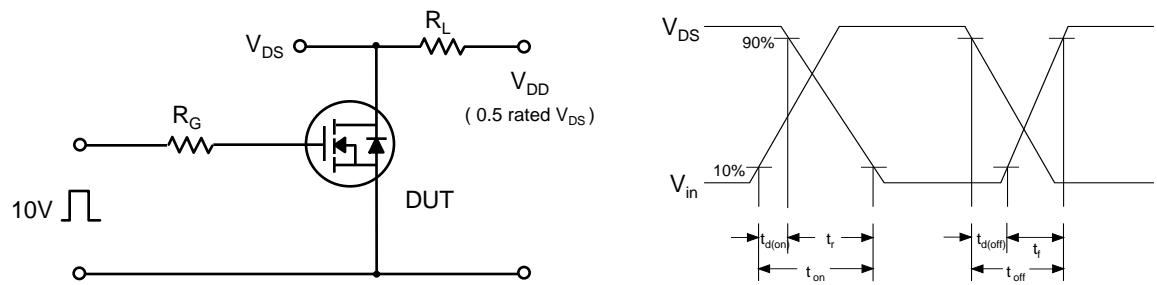


Fig 14. Unclamped Inductive Switching Test Circuit & Waveforms

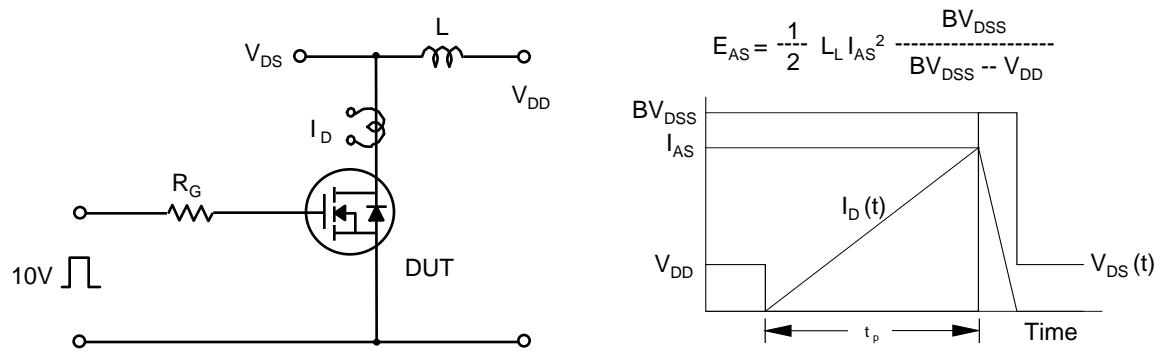
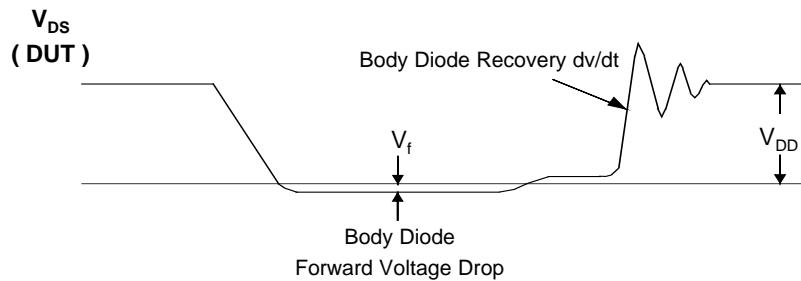
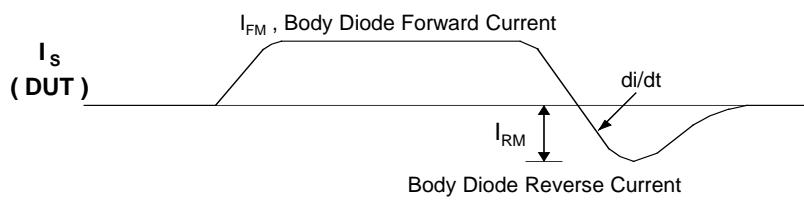
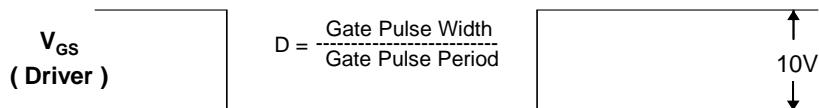
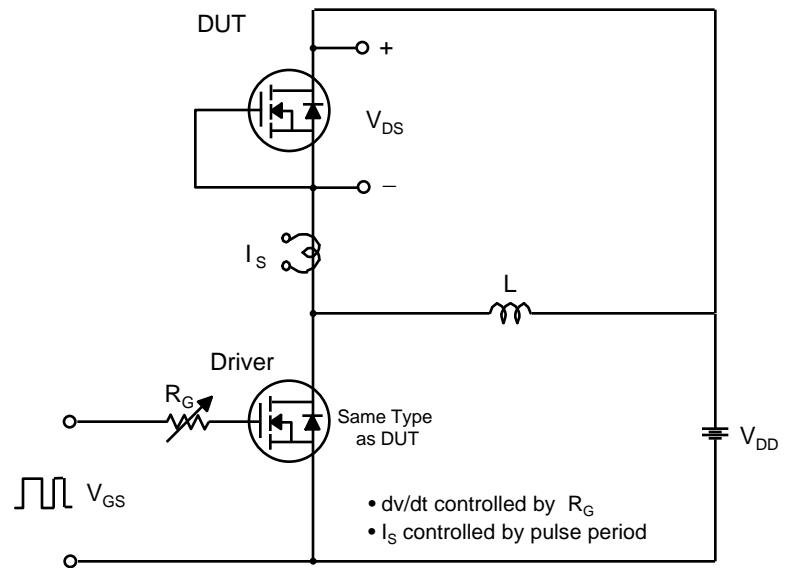


Fig 15. Peak Diode Recovery dv/dt Test Circuit &amp; Waveforms



**Package Dimension****8DFN 5x6**